

LOW-PRESSURE MOLDING

Moldman Systems LLC 4649 Aircenter Circle, Ste. 101 Reno, Nevada 89502

> Main 775-332-1600 Fax 775-332-1601

moldmansystems.com contactus@moldmansystems.com

Elemelt Technical Data Sheet TC-960-0R02-B

Elemelt TC-960-0R02-B is a high molecular weight copolyester resin designed for low pressure molding. This resin has the characteristics of a short open time with a high melting point. Application temperature is 180-210°C which is ideal for PCB encapsulation and durability. Adhesion can be improved with plasma treating or by coating chemical primer. This product is available in black.

1. TYPICAL SPECIFICATIONS

Appearance	: Black pellet solid.
Melting Point(°C)	: 160 ~ 170
Viscosity(dPa·s/220°C)	: 200 ~ 300
Acid Value (mg-KOH/gm)	: 3 Max.
Specific Gravity	: 1.11

2. SHORE-A HARDNESS

Measured Temperature °C	Shore-A Hardness
23	92
40	90
60	85
80	83
100	77
120	68

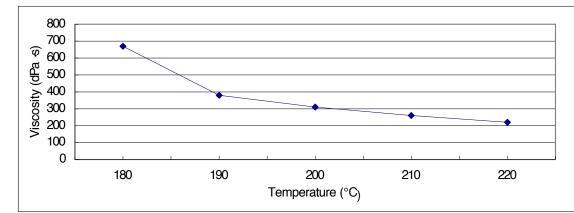
3. WATER ABSORBTION

Water Absorbtion(%)

: 0.4(RH23°C 50%,1Day)







4. VISCOSITY CURVE VERSUS TEMPERATURE

5. APPLICATION TEMPERATURE

180°C ~210°C

6. PACKAGING

20 kg net, paper bag.

7. STORAGE CONDITIONS

Store in sealable container once shipping bag has been opened. Copolyesters are sensitive to high humidity and will absorb atmospheric moisture. <u>Be sure to dry polyester resin at 60°C for more than 4 hours before use.</u> Shelf life is 6 months with proper storage and at a temperature below 30°C.

Note:

Our data and recommendations in this sheet do not constitute a warranty or representation for which we assume legal responsibility. They are offered only for your reference, investigation and verification, not guaranteed values.

Before using this product, please check or study carefully, that this grade is suitable for your purpose, application and process condition, etc.